Forward-looking Statement

- Information included in this presentation that are not historical in nature are "forward-looking statements". C Sun cautions readers that forward looking statements are based on C Sun's reasonable knowledge and current expectations and are subject to various risks and uncertainties.

- Actual results may differ materially from those contained in such forward-looking statements for a variety of reasons including without limitation, risks associated with demand and supply change, manufacturing and supply capacity, design in, time to market, market competition, industrial cyclicality, customer's financial condition, exchange rate fluctuation, legal actions, amendments of the laws and regulations. global economy change, natural disasters, and other unexpected events which may disrupt C Sun's business and operations.

- Accordingly, readers should not place reliance on any forward-looking statements. Except as required by law. C Sun undertakes no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.

先進封裝協作型技術團隊

透過高度協作能力，讓不同體系客戶都能成功

C SUN 志聖工業

2026 Q1 Investor’s meeting

元大第一季投資論壇 2026.03.03

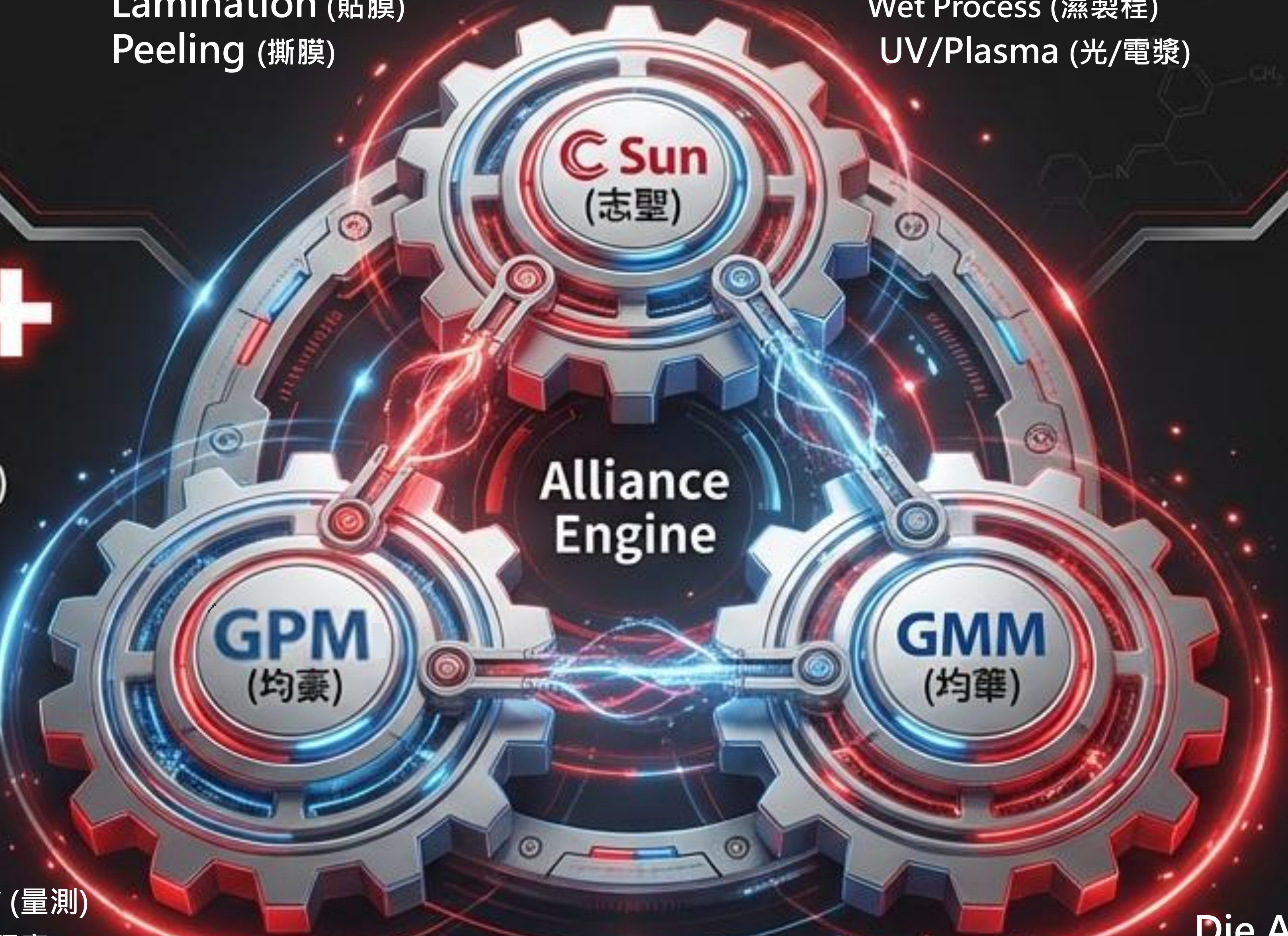
G2C+
T STRATEGY ALLIANCE

G2C+ 聯盟：平台化作戰優勢
G2C+ Alliance: The Platform Advantage

Bonder (壓合)
Lamination (貼膜)
Peeling (撕膜)

Thermal (熱)
Wet Process (濕製程)
UV/Plasma (光/電漿)

1,800+
聯盟總人數
(Total Alliance Workforce)



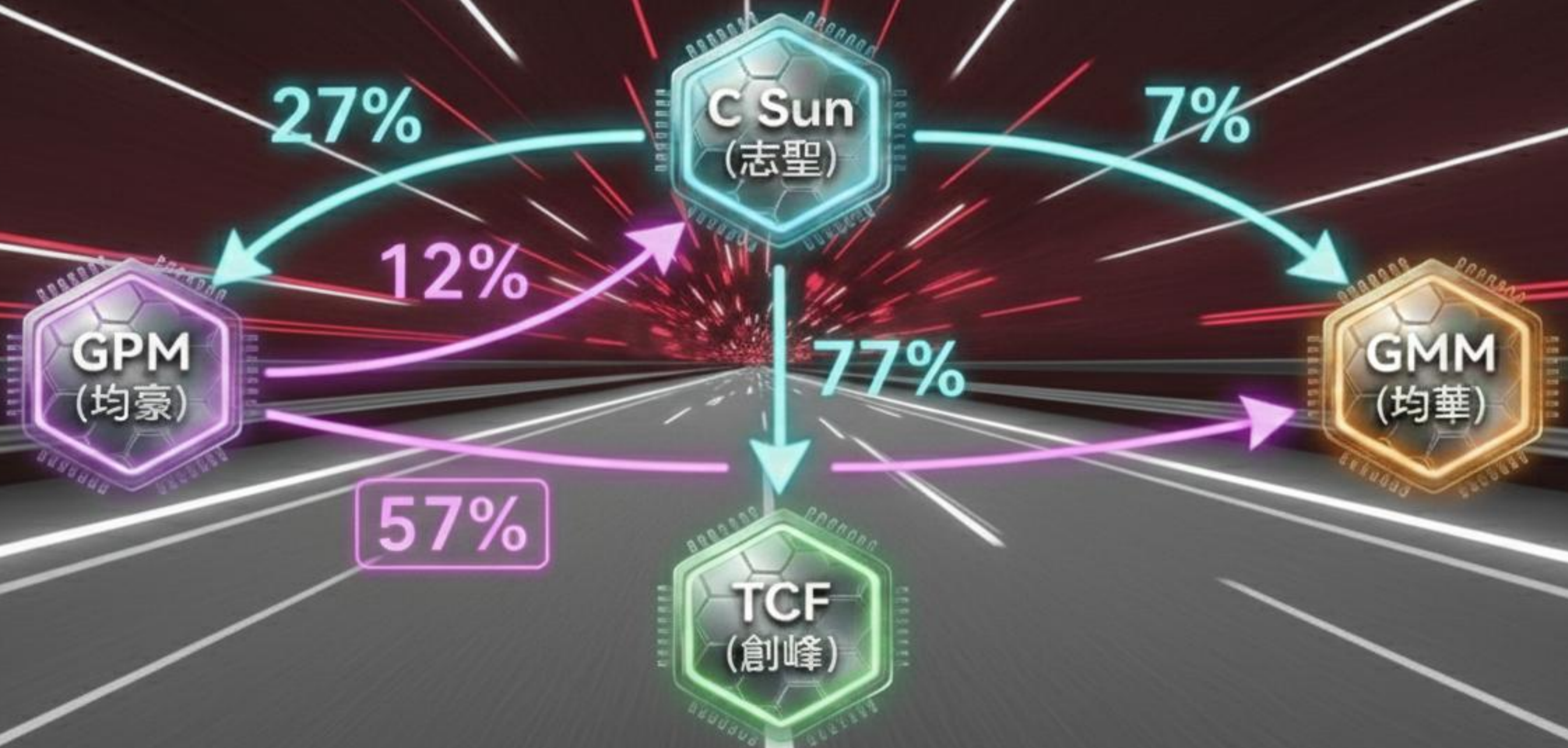
>600
研發人員
(R&D Personnel)

AOI (檢測)
Metrology (量測)
Grinding (研磨)
Polishing (拋光)

Die Attach (黏晶)
Chip Sorter (揀晶)

研發團隊規模成長
軟體 + 機構

Cross Holding Structure



GPM = 均豪 ｜ GMM = 均華 ｜ C Sun = 志聖

AI賽道上的專業協作團隊

連續獲得冠軍車隊肯定

2023:
Excellent Production Support
(卓越量產支援)

2024:
Outstanding Improvement
(傑出持續改善)

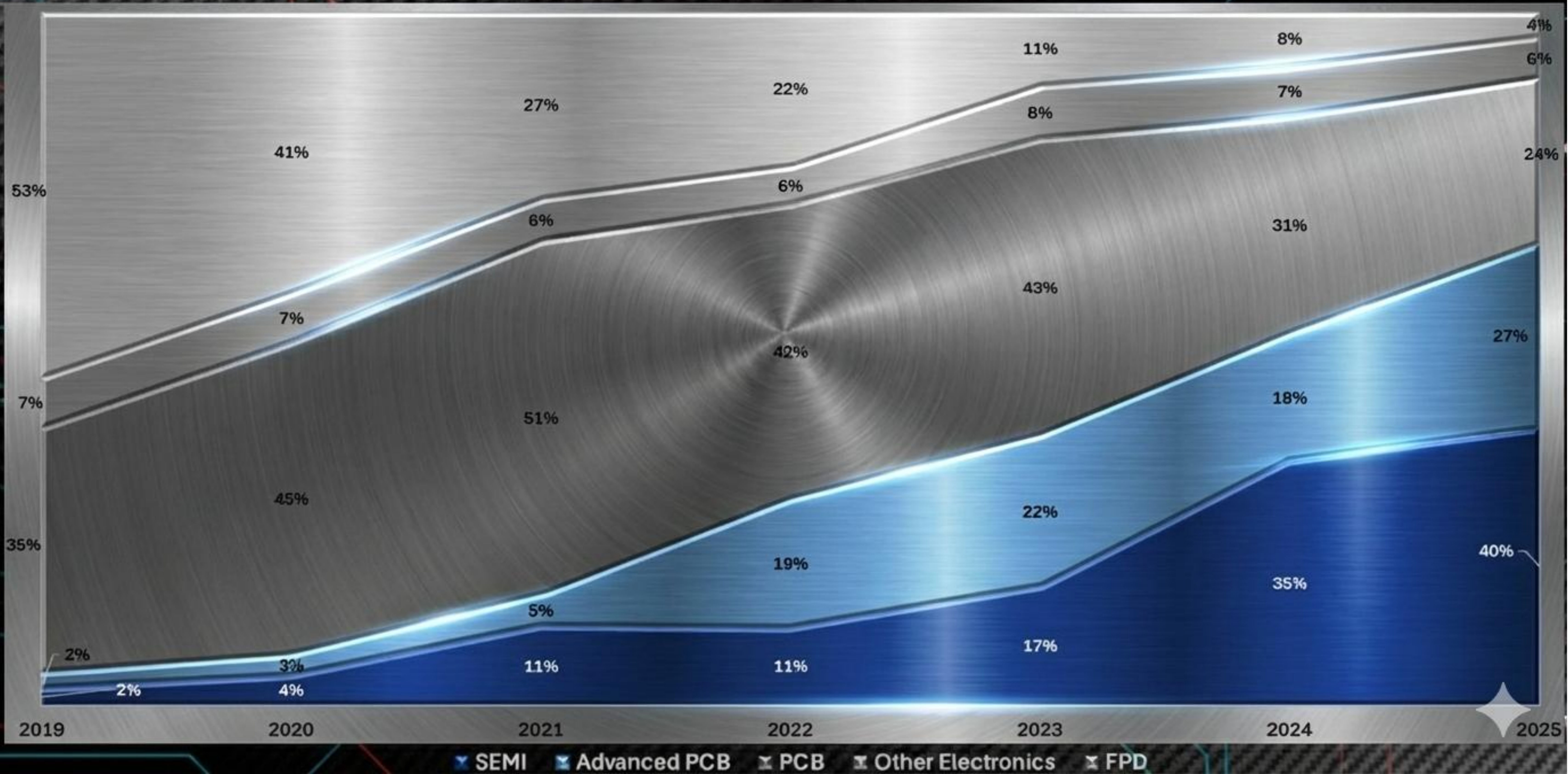
2025:
Excellent Production Support
(卓越量產支援)

財務回顧

(除另予註明者外，金額為新台幣百萬元)

	2026 Jan	2025	4Q25	3Q25	1H25	2024	4Q25 QoQ	2025 YoY
營業收入淨額	994	6,102	1,747	1,536	2,819	4,818	13.7%	26.6%
營業毛利率%		43.3%	44.1%	44.2%	42.3%	41.2%	-0.1ppts	+2.1ppts
營業費用		(1,760)	(493)	(526)	(741)	(1,347)	-6.3%	30.7%
營業費用率%		28.9%	28.2%	34.3%	30.5%	28.0%	-2.3ppts	+0.9ppts
研發費用		(543)	(170)	(164)	(208)	(362)	3.9%	49.8%
研發費用率%		8.9%	9.8%	10.7%	7.4%	7.5%	-0.9ppts	+1.4ppts
營業利益率%		14.5%	15.9%	10.0%	16.1%	13.2%	+5.9ppts	+1.3ppts
營業外收入與支出		243	56	134	54	344	-58.4%	-29.1%
歸屬予母公司業主之本期淨利		830	260	212	358	719	23.1%	15.4%
純益率%		13.6%	14.9%	13.8%	12.7%	14.9%	+1.1ppts	-1.3ppts
每股盈餘(新台幣元)		5.5	1.72	1.4	2.38	4.8	22.9%	14.6%

Revenue Composition

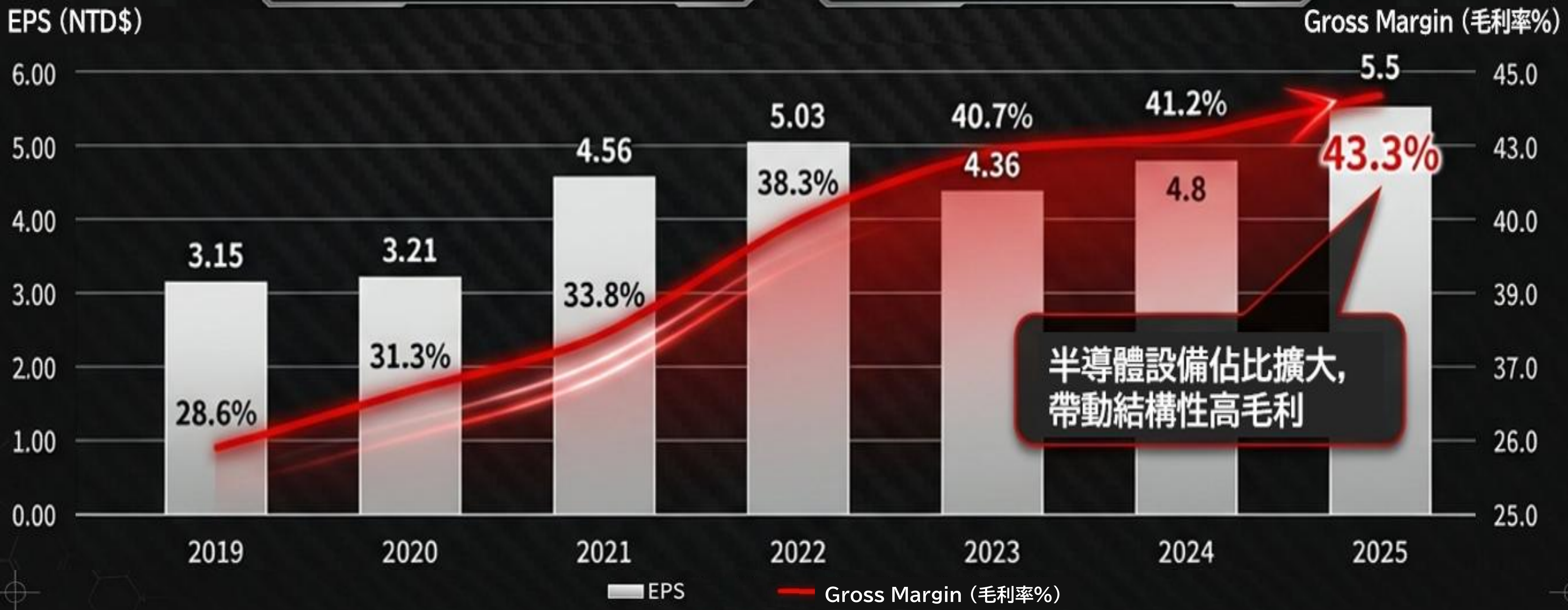


財務亮點：結構性蛻變與獲利創高

Scoreboard

2025 營收 (Revenue)
61 億元 Record High (創歷史新高)

2025 EPS
5.50 元



2026年開局：單月營收創新高

MoM
+64.60%

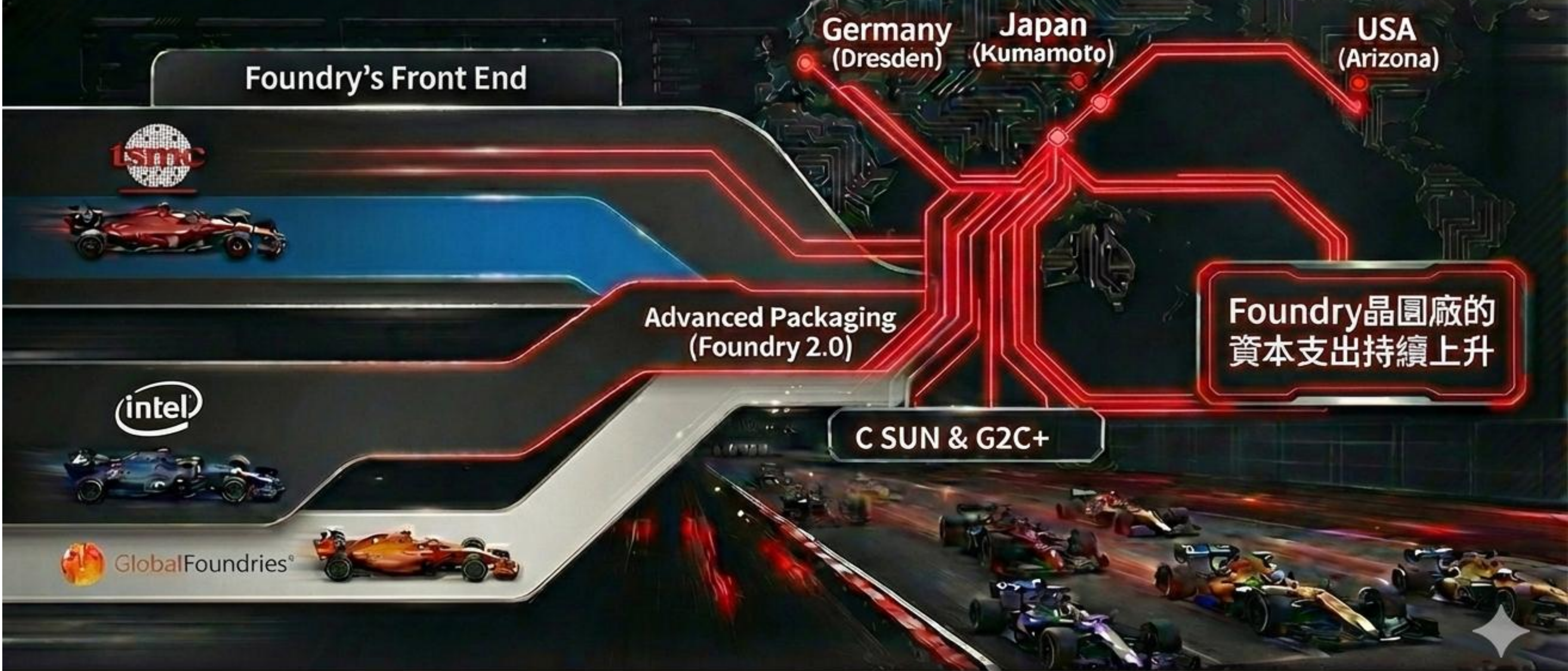
YoY
+124.10%

客戶資本支出持續投入，未來成長動能具延續性。配合客戶交期需求。

TSMC, intel, GF
FOUNDRY ACCESS TRACK
SoIC
InFO
EMIB
X-CUBE
WMCM
TSMC | intel | GF
OSAT
AI substrate & HDI
AI SUBSTRATE & HDI
ACCESS TRACK
ABF
SAP
HDI
mSAP
OSAT
ACCESS TRACK
Adv. PLP
SoIC
InFO
FlipChip
FoCoS
FoPLP
CoWoS
CoWoS
CoWoP
Advanced Packaging
GRAND CIRCUIT
GRAND CIRCUIT
GRAND CIRCUIT
mSAP
CoWoP
CoWoS

成長引擎I：跟隨領航者 晶圓廠全球在地化

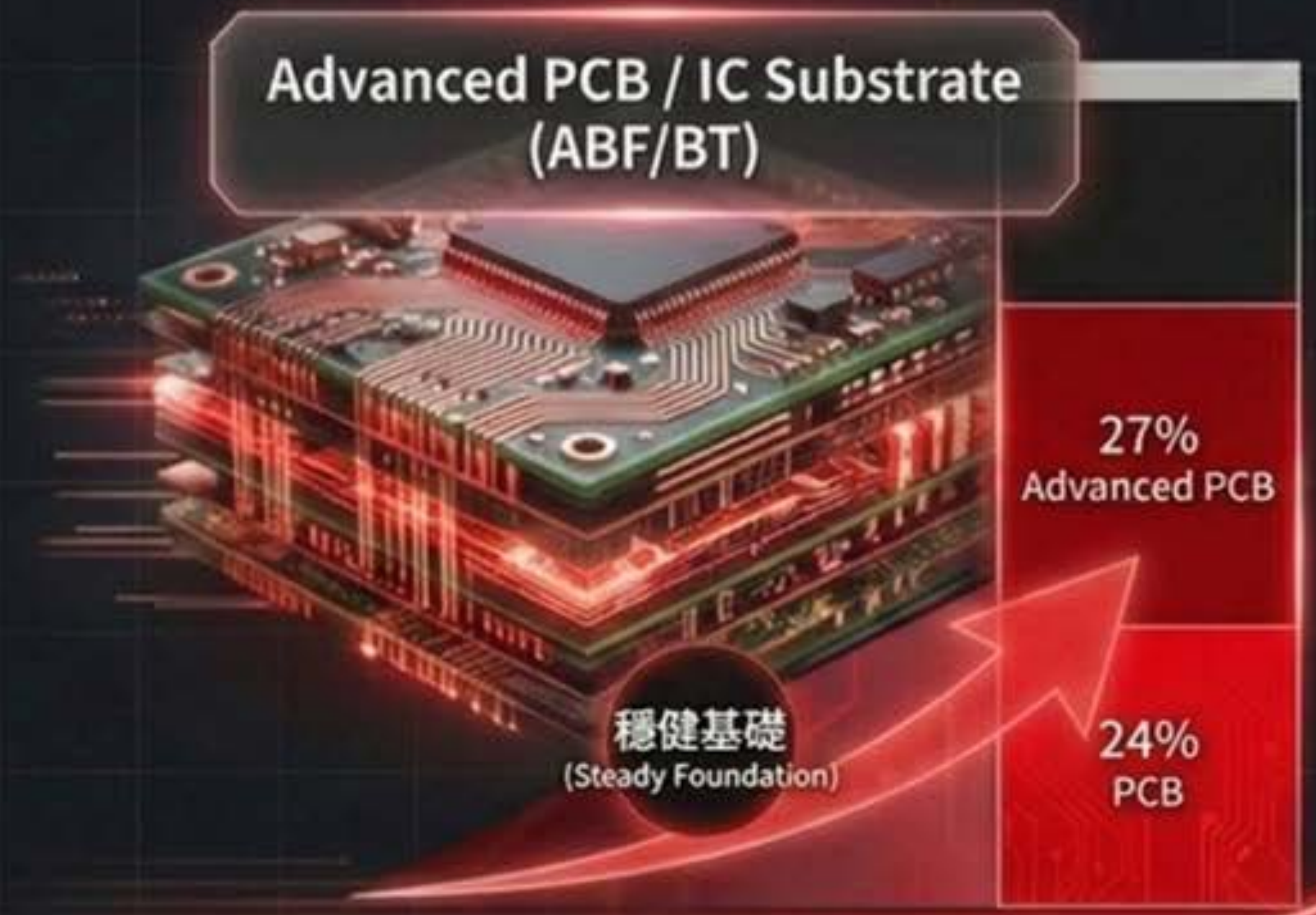
- Foundry 2.0 Glocalization 的大戰略



成長引擎II：AI晶片多元化帶動製程分流與封裝技術外溢

成長引擎 III：高階PCB產品占比提升及區域移動

Foundation & Expansion Strategy



產品組合優化帶動**平均售價提升**，獲利結構持續改善。

研發資源配置與技術升級

R&D Resource Allocation & Tech Upgrade

先進封裝產業鏈新世代製程與設備升級
Next-Gen Processes & Equipment Upgrade for Advanced Packaging Supply Chain

技術升級期的投入將支持未來3-5年成長動能

技術藍圖：全方位製程覆蓋
Technology Roadmap: Full Spectrum Coverage

Technology Spark Matrix

Foundry
(晶圓代工)

- CoWoS
- SoIC
- WMCM
- Adv. PLP

OSAT
(封測廠)

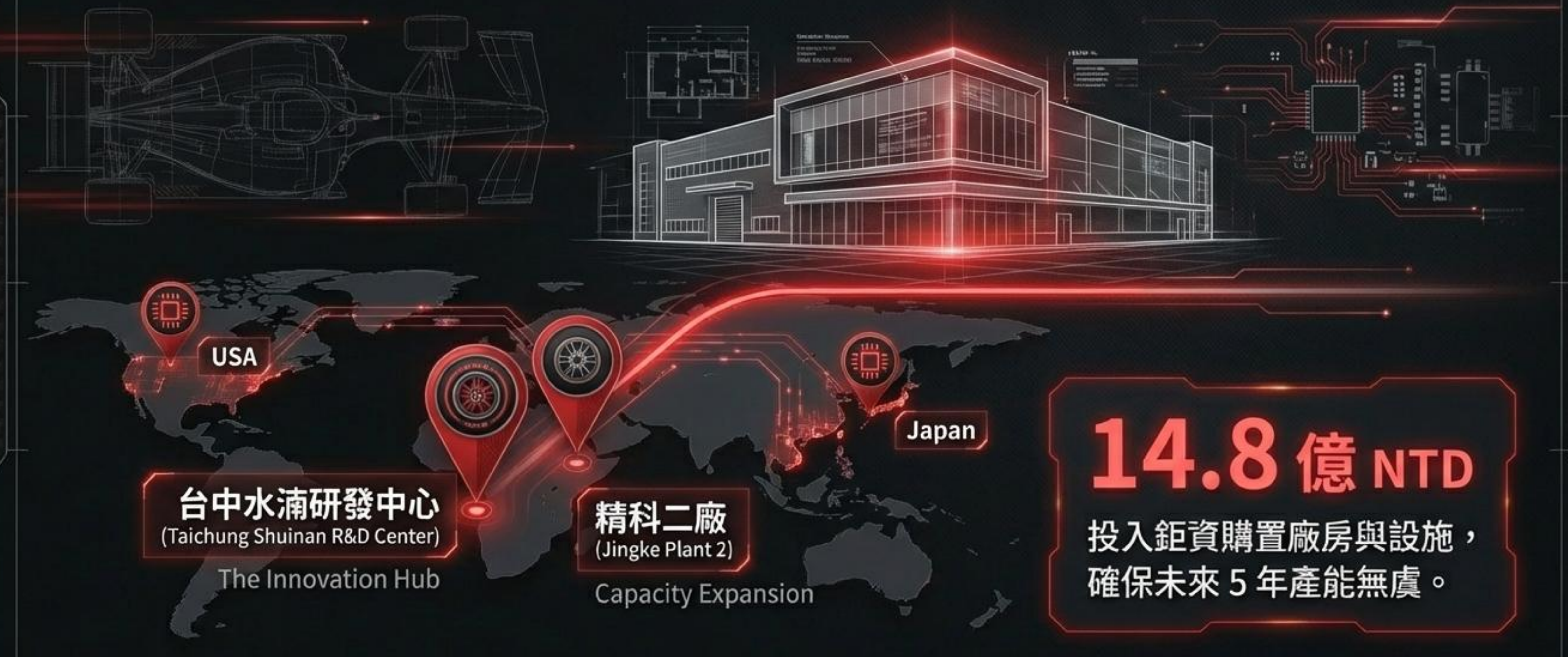
- oS
- BSM
- CoW
- CoWoP
- EMIB
- PLP (Panel Level Packaging)

Advanced PCB
(先進板廠)

- IC Substrate (載板)
- HDI
- CoWoP

不僅掌握現有先進製程紅利，更已佈局未來 3 年 新製程需求

築巢引鳳：研發中心與全球擴張



14.8 億 NTD

投入鉅資購置廠房與設施，
確保未來 5 年產能無虞。

ROBOTO MONO　Noto Sans TC Medium　TELEMETRY　STATUS: OPTINAL　PROCESS LOOP: ACT2VE　TEMP: 400°C


F1先進封裝大賽
Foundry 主賽道
CoWoS / SoIC / WMCM
TSMC
tsmc
OSAT 賽道
PLP / oS / Bumping / CoW / EMIB
ASE
PTI
AI載板多層板賽道
IC Substrate / HDI
Unimicron
Zhen Ding
G2C+